



SOLDER CONNECTION

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QUALITEK® Technical Bulletin

PF608 No Clean Paste Flux

DESCRIPTION

PF608 is a Halide-Free No Clean paste flux (also known as tacky flux) designed for PCB assembly and rework applications. PF608 was originally designed for Lead-Free applications but may be used for both Leaded and Lead-Free circuit board assembly and rework applications. PF608 post-soldering residues are non-corrosive and non-conductive. PF608 is available in syringes for easy dispensing or in jars.

FEATURES & BENEFITS

- Robust tacky flux
- Halide-Free
- Non-corrosive/Non-conductive residues
- May be used for Leaded and Lead-Free applications

TECHNICAL DATA

	Specification	Test Method
Flux Classification	ROLO	IPC-J-STD-004B
Colour & Appearance	Light amber semi-solid	
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Corrosion	Pass	IPC-TM-650 2.6.15
SIR	>1.0 x 10 ⁸ ohms	IPC-TM-650 2.6.3.3
pH (5% Aqueous Solution)	3.9 ± 0.5	
Conductivity(µS/cm)	19.0 ± 5.0	
Shelf Life	1 Year from DOM	

APPLICATION METHODS

Paste Fluxes are recommended for touch up and repair of surface mount assemblies. Paste Fluxes may be applied by brushing, dipping or dispensing onto the appropriate areas, then heated using conventional methods.

RESIDUE REMOVAL

PF608 residues are non-corrosive, non-conductive, so residue removal is not required. If removal of post soldering residues is desired, we recommend using Qualitek Everkeen 1005 Buffered Saponifier.

DISPOSAL

Paste Flux should be stored in a sealed container and disposed of in accordance with federal, state and local authority requirements.

PACKAGING

- 8 gram 10 cc Syringes
- 24 gram 30 cc Syringes
- 50 gram 3 oz. Jars
- 100 gram 4 oz. Jars

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